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TIDA-01322 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	PCB	1		TIDA-01322	Any	Printed Circuit Board	
2	C1, C3	2	22uF	C3216X5R0J226M	TDK	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 1206	1206
3	C2	1	0.47uF	0805YC474JAT2A	AVX	CAP, CERM, 0.47 µF, 16 V, +/- 5%, X7R, 0805	0805
4	C4, C5	2	47uF	C3216X5R0J476M	TDK	CAP, CERM, 47 µF, 6.3 V, +/- 20%, X5R, 1206	1206
5	C6	1	0.12uF	GRM188R71A124KA01D	MuRata	CAP, CERM, 0.12 µF, 10 V, +/- 10%, X7R, 0603	0603
6	C7, C8	2	22uF	C1210C226K9RACTU	Kemet	CAP, CERM, 22 µF, 6.3 V, +/- 10%, X7R, 1210	1210
7	C9	1	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X7R, 0603	0603
8	Gnd1, Gnd2, Gnd3, Gnd4, Gnd5, Gnd6, TP_En, TP_Pg, TP_PG1, TP_PG2, TP_Vin, TP_Vout1, TP_Vout2, TP_Vout_LDO, TPSs	15	Double	1502-2	Keystone	Terminal, Turret, TH, Double	Keystone1502-2
9	J1, J5, J7	3		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
10	J2, J4, J6	3		HTSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	Header, 100mil, 3x1, TH
11	J3, J8, J9	3		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
12	L1, L2	2	1uH	DFE252012PD-1R0M	MuRata Toko	Inductor, Shielded, 1 µH, 3.8 A, 0.035 ohm, AEC-Q200 Grade 1, SMD	1008
13	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
14	R1	1	4.99	CRCW08054R99FKEA	Vishay-Dale	RES, 4.99, 1%, 0.125 W, 0805	0805
15	R2, R4, R6, R7, R10	5	10.0k	CRCW040210K0DHEDP	Vishay-Dale	RES, 10.0 k, 0.5%, 0.063 W, 0402	0402
16	R3	1	619	CRCW0402619RFKED	Vishay-Dale	RES, 619, 1%, 0.063 W, 0402	0402
17	R5	1	16.2k	CRCW040216K2FKED	Vishay-Dale	RES, 16.2 k, 1%, 0.063 W, 0402	0402
18	R8	1	32.4k	CRCW040232K4FKED	Vishay-Dale	RES, 32.4 k, 1%, 0.063 W, 0402	0402
19	R9	1	12.4k	CRCW040212K4FKED	Vishay-Dale	RES, 12.4 k, 1%, 0.063 W, 0402	0402
20	U1	1		LM26420XSQXNOPB	Texas Instruments	Dual 2-A, High Frequency Synchronous Buck Regulator, RUM0016A (WQFN-16)	RUM0016A
21	U2	1		LP592201DSCR	Texas Instruments	LP592201, DSC0010J	DSC0010J
22	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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